

## SOP-8 Plastic-Encapsulate MOSFET

### 30V P-Channel MOSFET

#### Product Summary

$V_{(BR)DSS}$	$R_{DS(on)TYP}$	$I_D$
-30V	18mΩ@-10V	-9.1A
	26mΩ@-4.5V	

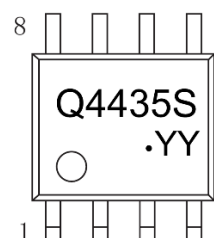
#### Feature

- TrenchFET Power MOSFET
- Excellent  $R_{DS(on)}$
- Low Gate Charge

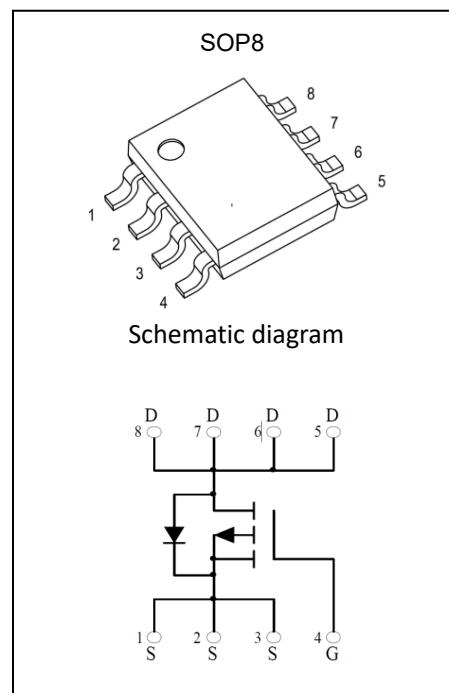
#### Application

- Load Switch for Portable Devices
- Battery Switch

#### MARKING:



Q4435S = Device code  
 YY = Date Code  
 Solid dot = Pin1 indicator  
 Solid dot = Green molding compound device,  
 If none, the normal device.



#### ABSOLUTE MAXIMUM RATINGS ( $T_a=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	-30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current	$I_D$	-9.1	A
Pulsed Drain Current	$I_{DM}$	-27	A
Power Dissipation	$P_D$	2.7	W
Thermal Resistance from Junction to Ambient( $t \leq 10s$ )	$R_{\theta JA}$	46	$^{\circ}\text{C/W}$
Thermal Resistance from Junction to Board	$R_{\theta JB}$	8.6	$^{\circ}\text{C/W}$
Thermal Resistance from Junction to Case	$R_{\theta JC}$	4	$^{\circ}\text{C/W}$
Junction Temperature	$T_J$	150	$^{\circ}\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^{\circ}\text{C}$

## Electrical Characteristics ( $T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = -250\mu A$	-30			V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = -30V, V_{GS} = 0V$			-1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$			$\pm 0.1$	$\mu A$
<b>On characteristics<sup>(1)</sup></b>						
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.5	-3.0	V
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = -10V, I_D = -9.1A$		18	24	$m\Omega$
		$V_{GS} = -4.5V, I_D = -6.9A$		26	35	
Forward transconductance	$g_{FS}$	$V_{DS} = -10V, I_D = -9.1A$		12		S
<b>Dynamic characteristics<sup>(2)</sup></b>						
Input capacitance	$C_{iss}$	$V_{DS} = -15V, V_{GS} = 0V, f = 1MHz$		1400		$pF$
Output capacitance	$C_{oss}$			163		
Reverse transfer capacitance	$C_{rss}$			145		
<b>Switching characteristics<sup>(2)</sup></b>						
Total gate charge	$Q_g$	$V_{DS} = -15V, V_{GS} = -4.5V, I_D = -9.1A$			25	$nC$
Gate-source charge	$Q_{gs}$				7	
Gate-drain charge	$Q_{gd}$				12	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = -15V, I_D = -1A, V_{GS} = -10V, R_G = 1\Omega, R_L = 15\Omega$			15	$ns$
Turn-on rise time	$t_r$				15	
Turn-off delay time	$t_{d(off)}$				70	
Turn-off fall time	$t_f$				25	
<b>Drain-Source Diode Characteristics</b>						
Drain-source diode forward voltage <sup>(1)</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = -2A$			-1.2	V
Continuous drain-source diode forward current	$I_S$				-9.1	A
Pulsed drain-source diode forward current	$I_{SM}$				-27	

### Notes:

1. Pulse test; pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
2. Guaranteed by design, not subject to production testing.

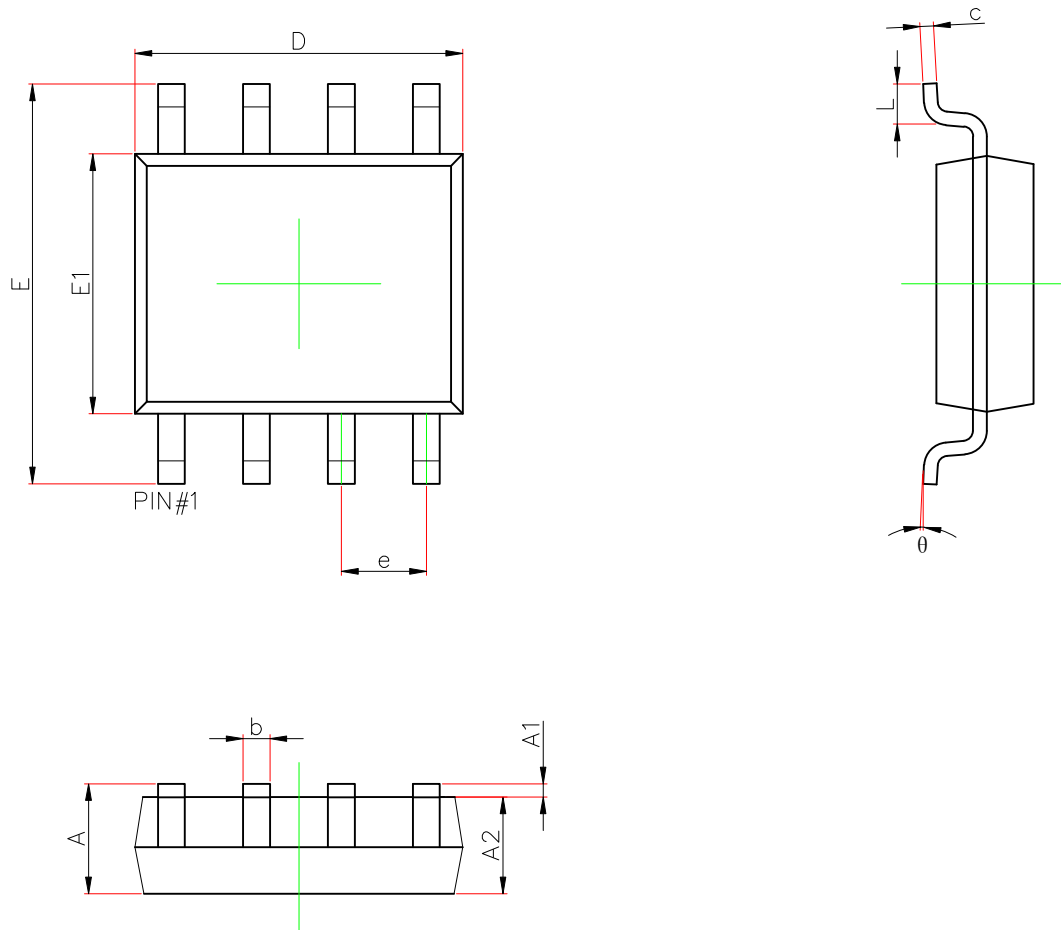
**MOSFET ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25°C unless otherwise noted)**

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250μA	-30			V
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = -30V, V <sub>GS</sub> = 0V			-1	μA
Gate-body leakage current	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±0.1	μA
<b>On characteristics<sup>(1)</sup></b>						
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250μA	-1.0	-1.5	-3.0	V
Drain-source on-resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -9.1A		18	24	mΩ
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -6.9A		26	35	
Forward transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -9.1A		12		S
<b>Dynamic characteristics<sup>(2)</sup></b>						
Input capacitance	C <sub>iSS</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V, f = 1MHz		1400		pF
Output capacitance	C <sub>oSS</sub>			163		
Reverse transfer capacitance	C <sub>rSS</sub>			145		
<b>Switching characteristics<sup>(2)</sup></b>						
Total gate charge	Q <sub>g</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -9.1A			25	nC
Gate-source charge	Q <sub>gs</sub>				7	
Gate-drain charge	Q <sub>gd</sub>				12	
Turn-on delay time	t <sub>d(on)</sub>	V <sub>DD</sub> = -15V, I <sub>D</sub> = -1A, V <sub>GS</sub> = -10V, R <sub>G</sub> = 1Ω, R <sub>L</sub> = 15Ω			15	ns
Turn-on rise time	t <sub>r</sub>				15	
Turn-off delay time	t <sub>d(off)</sub>				70	
Turn-off fall time	t <sub>f</sub>				25	
<b>Drain-Source Diode Characteristics</b>						
Drain-source diode forward voltage <sup>(1)</sup>	V <sub>SD</sub>	V <sub>GS</sub> = 0V, I <sub>S</sub> = -2A			-1.2	V
Continuous drain-source diode forward current	I <sub>S</sub>				-9.1	A
Pulsed drain-source diode forward current	I <sub>SM</sub>				-27	

**Notes:**

1. Pulse test; pulse width ≤ 300μs, duty cycle ≤ 2%.
2. Guaranteed by design, not subject to production testing.

## SOP-8 Package Outline Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.156	0.250	0.006	0.010
D	4.700	5.100	0.185	0.201
e	1.270(BSC)		0.050(BSC)	
E	5.800	6.200	0.228	0.244
E1	3.700	4.100	0.146	0.161
L	0.400	1.270	0.016	0.05
theta	0°	8°	0°	8°

### NOTICE

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